


Insulated Gate Bipolar Transistor

Ultralow $V_{CE(on)}$, 250 A



SOT-227

FEATURES

- Standard: Optimized for minimum saturation voltage and low speed up to 5 kHz
- Lowest conduction losses available
- Fully isolated package (2500 V_{AC})
- Very low internal inductance (5 nH typical)
- Industry standard outline
- Designed and qualified for industrial level
- UL approved file E78996 
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

PRODUCT SUMMARY

V_{CES}	600 V
$V_{CE(on)}$ (typical) at 200 A, 25 °C	1.33 V
I_C at $T_C = 90$ °C ⁽¹⁾	250 A

Note

- ⁽¹⁾ Maximum collector current admitted 100 A to do not exceed the maximum temperature of terminals

BENEFITS

- Designed for increased operating efficiency in power conversion: UPS, SMPS, TIG welding, induction heating
- Easy to assemble and parallel
- Direct mounting to heatsink
- Plug-in compatible with other SOT-227 packages

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		600	V
Continuous collector current	I_C ⁽¹⁾	$T_C = 25$ °C	400	A
		$T_C = 90$ °C	250	
Pulsed collector current	I_{CM}	Repetitive rating; $V_{GE} = 20$ V, pulse width limited by maximum junction temperature	400	
Clamped Inductive load current	I_{LM}	$V_{CC} = 80$ % (V_{CES}), $V_{GE} = 20$ V, $L = 10$ μ H, $R_g = 2.0$ Ω ,	400	
Gate to emitter voltage	V_{GE}		± 20	V
Power dissipation	P_D	$T_C = 25$ °C	961	W
		$T_C = 90$ °C	462	
Isolation voltage	V_{ISOL}	Any terminal to case, $t = 1$ minute	2500	V

Note

- ⁽¹⁾ Maximum collector current admitted 100 A to do not exceed the maximum temperature of terminals

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature	T_J, T_{STG}	- 40	-	150	°C
Junction to case thermal resistance	R_{thJC}	-	-	0.13	°C/W
Case to sink thermal resistance, flat, greased surface	R_{thCS}	-	0.1	-	
Mounting torque, on terminals and heatsink	T	-	-	1.3	Nm
Weight		-	30	-	g
Case style	SOT-227				



ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{ V}$, $I_C = 1\text{ mA}$	600	-	-	V
Emitter to collector breakdown voltage	$V_{(BR)ECS}^{(1)}$	$V_{GE} = 0\text{ V}$, $I_C = 1.0\text{ A}$	18	-	-	
Collector to emitter voltage	$V_{CE(on)}$	$I_C = 100\text{ A}$	-	1.10	1.3	
		$I_C = 200\text{ A}$	-	1.33	1.66	
		$I_C = 100\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	1.02	-	
		$I_C = 200\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	1.32	-	
		$I_C = 100\text{ A}$, $T_J = 150\text{ }^{\circ}\text{C}$	-	1.02	-	
		$I_C = 200\text{ A}$, $T_J = 150\text{ }^{\circ}\text{C}$	-	1.33	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$	3.0	4.5	6.0	
		$V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	3.1	-	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$, $25\text{ }^{\circ}\text{C}$ to $125\text{ }^{\circ}\text{C}$	-	- 12	-	mV/ $^{\circ}\text{C}$
Collector to emitter leakage current	I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 600\text{ V}$	-	20	1000	μA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 600\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	0.2	-	mA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 600\text{ V}$, $T_J = 150\text{ }^{\circ}\text{C}$	-	0.6	10	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 20\text{ V}$	-	-	± 250	nA

Notes(1) Pulse width $\leq 80\text{ }\mu\text{s}$; duty factor $\leq 0.1\text{ }\%$

SWITCHING CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge (turn-on)	Q_g	$I_C = 100\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$	-	770	1200	nC
Gate-to-emitter charge (turn-on)	Q_{ge}		-	100	150	
Gate-to-collector charge (turn-on)	Q_{gc}		-	260	380	
Turn-on switching loss	E_{on}	$T_J = 25\text{ }^{\circ}\text{C}$ $I_C = 100\text{ A}$ $V_{CC} = 480\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 5.0\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$	-	0.55	-	mJ
Turn-off switching loss	E_{off}		-	25	-	
Total switching loss	E_{tot}		-	25.5	-	
Turn-on delay time	$t_{d(on)}$		-	267	-	ns
Rise time	t_r		-	42	-	
Turn-off delay time	$t_{d(off)}$		-	310	-	
Fall time	t_f		-	450	-	
Turn-on switching loss	E_{on}		-	0.67	-	mJ
Turn-off switching loss	E_{off}		-	43.0	-	
Total switching loss	E_{tot}		-	43.7	-	
Turn-on delay time	$t_{d(on)}$	$T_J = 125\text{ }^{\circ}\text{C}$ $I_C = 100\text{ A}$ $V_{CC} = 480\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 5.0\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$	-	275	-	ns
Rise time	t_r		-	50	-	
Turn-off delay time	$t_{d(off)}$		-	350	-	
Fall time	t_f		-	700	-	
Internal emitter inductance	L_E	Between lead and center of die contact	-	5.0	-	nH
Input capacitance	C_{ies}	$V_{GE} = 0\text{ V}$, $V_{CC} = 30\text{ V}$, $f = 1.0\text{ MHz}$	-	16 250	-	pF
Output capacitance	C_{oes}		-	1040	-	
Reverse transfer capacitance	C_{res}		-	190	-	

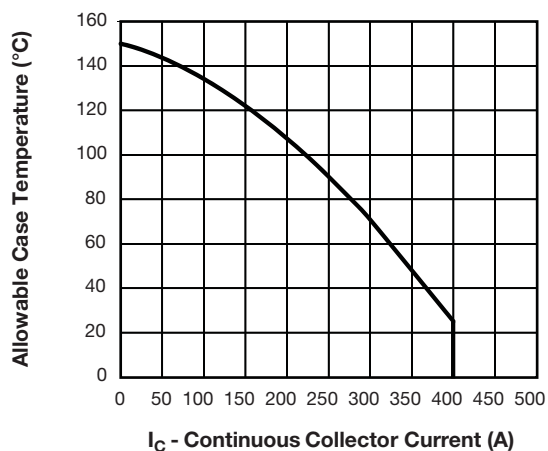


Fig. 1 - Maximum DC IGBT Collector Current vs. Case Temperature

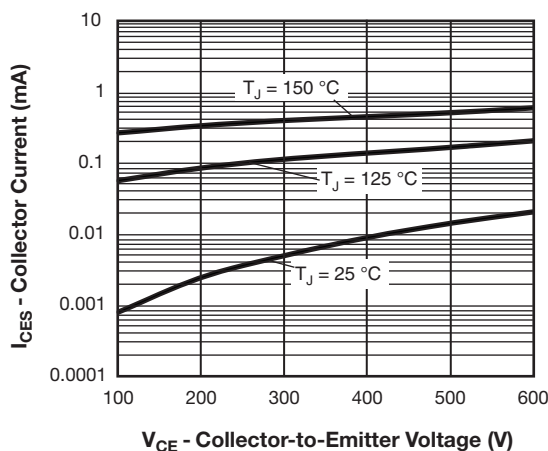


Fig. 4 - Typical IGBT Zero Gate Voltage Collector Current

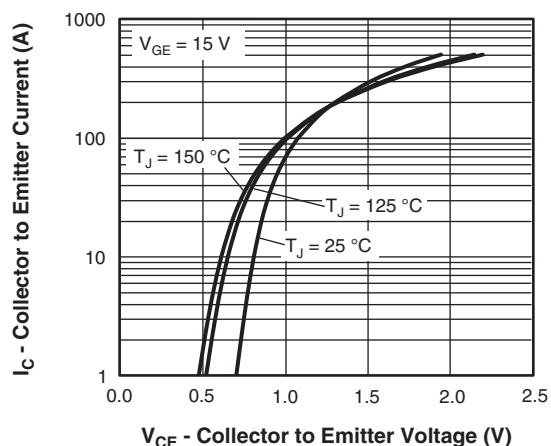


Fig. 2 - Typical Collector to Emitter Current Output Characteristics

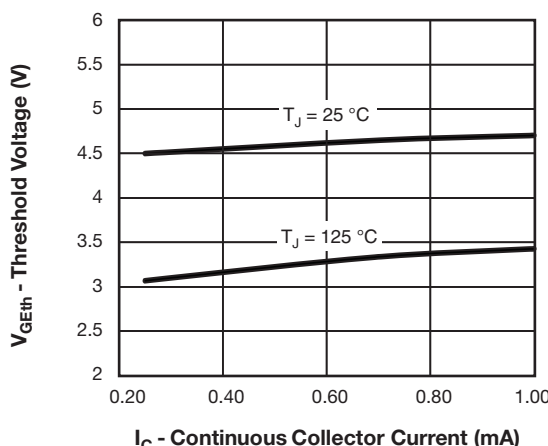


Fig. 5 - Typical IGBT Threshold Voltage

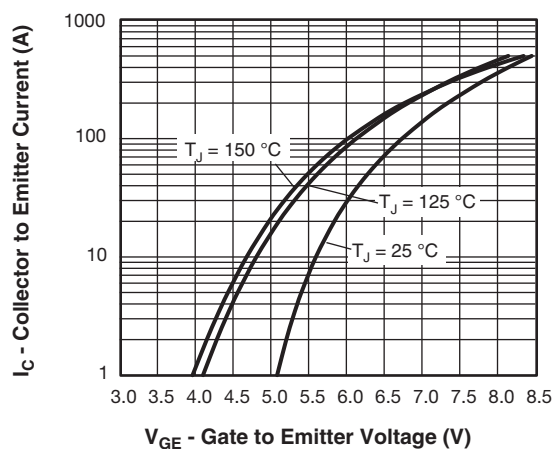
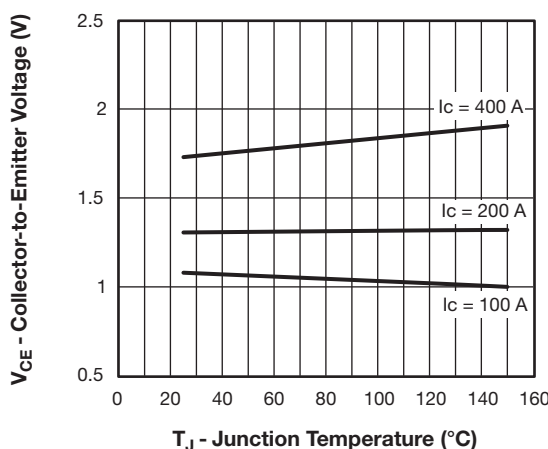


Fig. 3 - Typical IGBT Transfer Characteristics


Fig. 6 - Typical IGBT Collector to Emitter Voltage vs. Junction Temperature, $V_{GE} = 15\text{ V}$

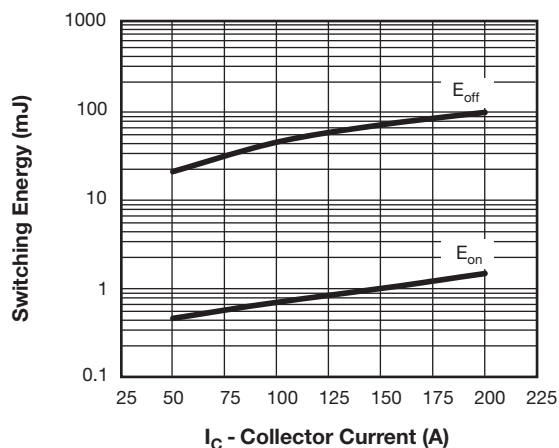


Fig. 7 - Typical IGBT Energy Losses vs. I_C , $T_J = 125^\circ\text{C}$, $V_{CC} = 480\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 5\text{ }\Omega$, Diode used: 60APH06

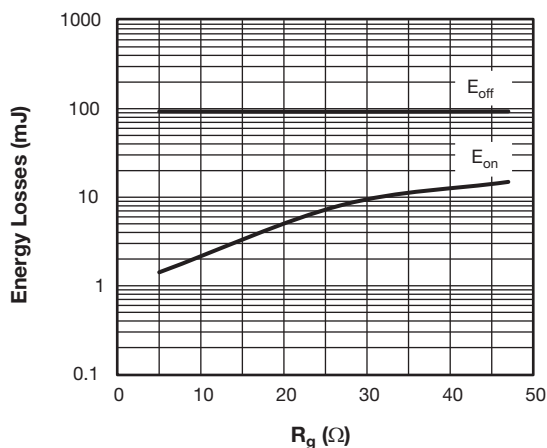


Fig. 9 - Typical IGBT Energy Losses vs. R_g , $T_J = 125^\circ\text{C}$, $I_C = 200\text{ A}$, $V_{CC} = 480\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, Diode used: 60APH06

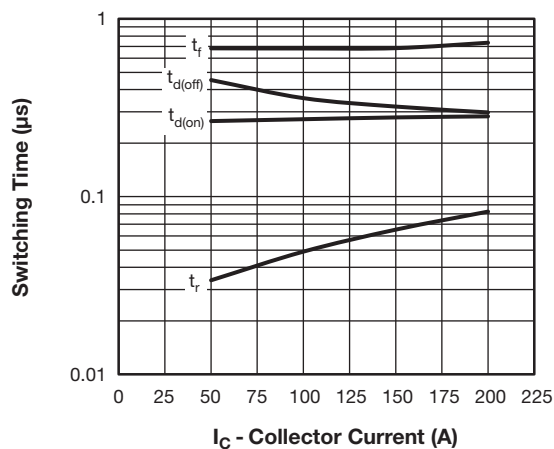


Fig. 8 - Typical IGBT Switching Time vs. I_C , $T_J = 125^\circ\text{C}$, $V_{CC} = 480\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 5\text{ }\Omega$, Diode used: 60APH06

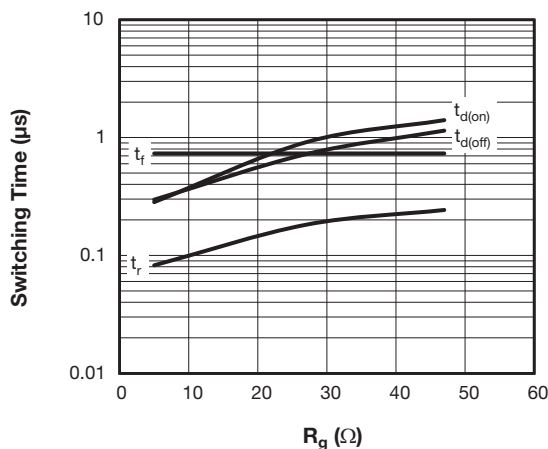


Fig. 10 - Typical IGBT Switching Time vs. R_g , $T_J = 125^\circ\text{C}$, $I_C = 200\text{ A}$, $V_{CC} = 480\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, Diode used: 60APH06

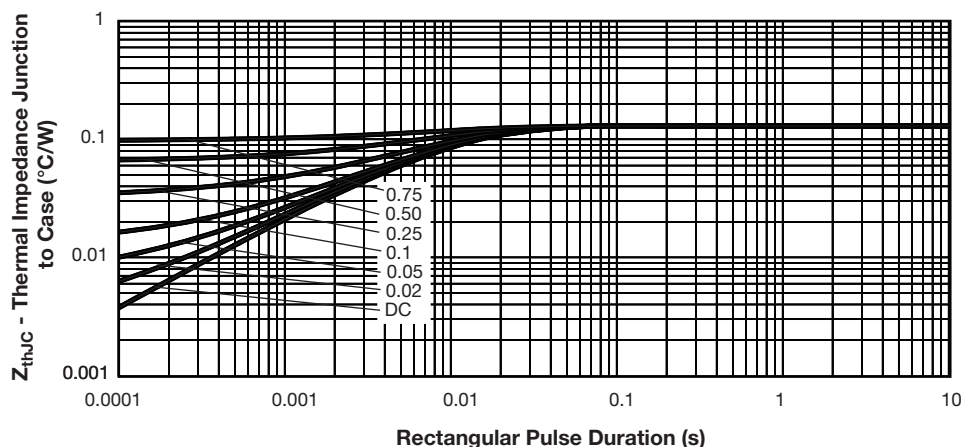


Fig. 11 - Maximum Thermal Impedance Z_{thJC} Characteristics

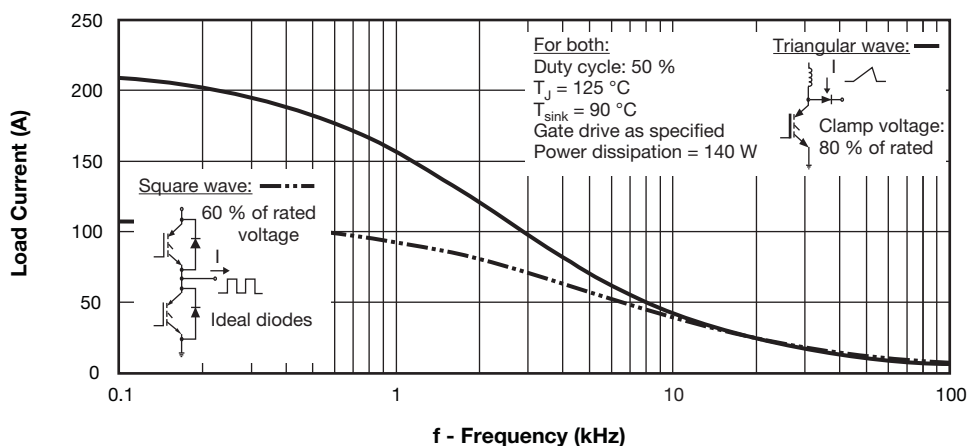


Fig. 12 - Typical Load Current vs. Frequency (Load Current = I_{RMS} of Fundamental)

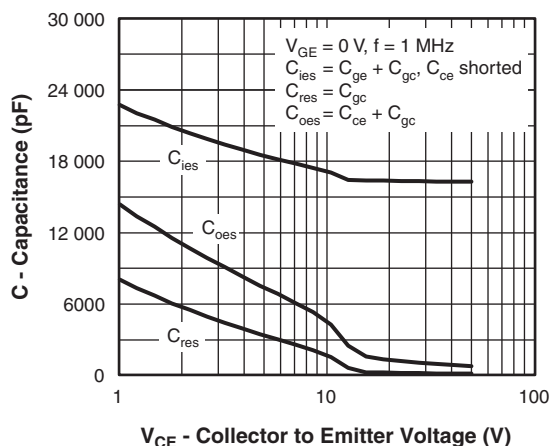


Fig. 13 - Typical Capacitance vs. Collector to Emitter Voltage

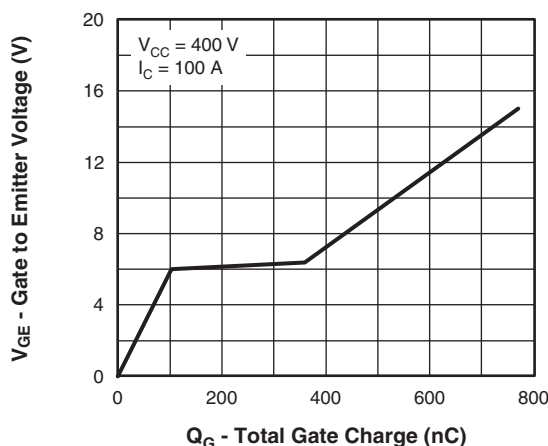


Fig. 14 - Typical Gate Charge vs. Gate to Emitter Voltage

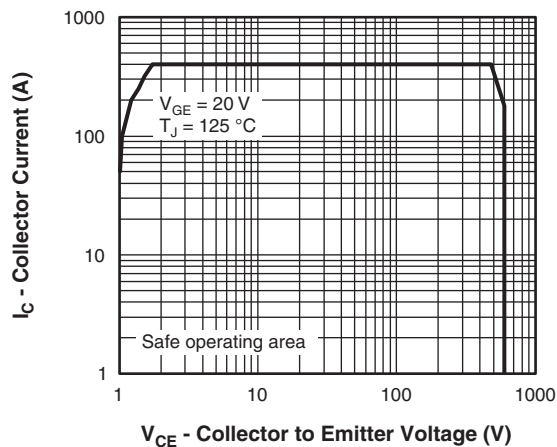
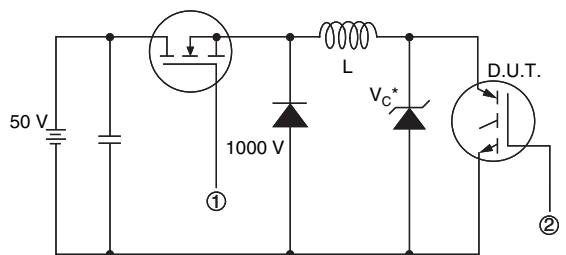


Fig. 15 - Turn-Off SOA



* Driver same type as D.U.T.; $V_C = 80\%$ of V_{CE} (max)

Note: Due to the 50 V power supply, pulse width and inductor will increase to obtain rated I_d

Fig. 16a - Clamped Inductive Load Test Circuit

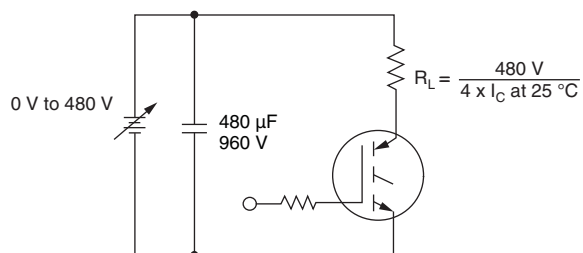
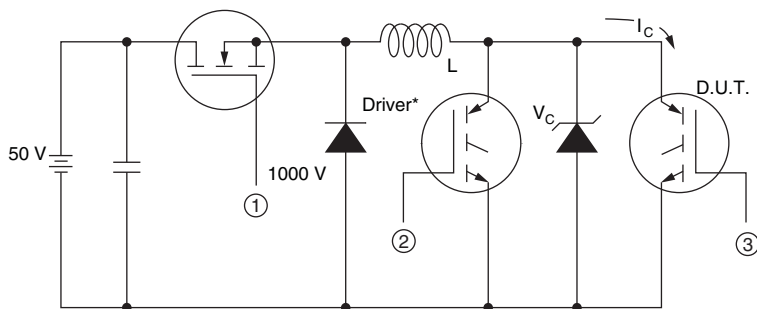


Fig. 16b - Pulsed Collector Current Test Circuit



* Driver same type as D.U.T., $V_C = 480\text{ V}$

Fig. 17a - Switching Lost Test Circuit

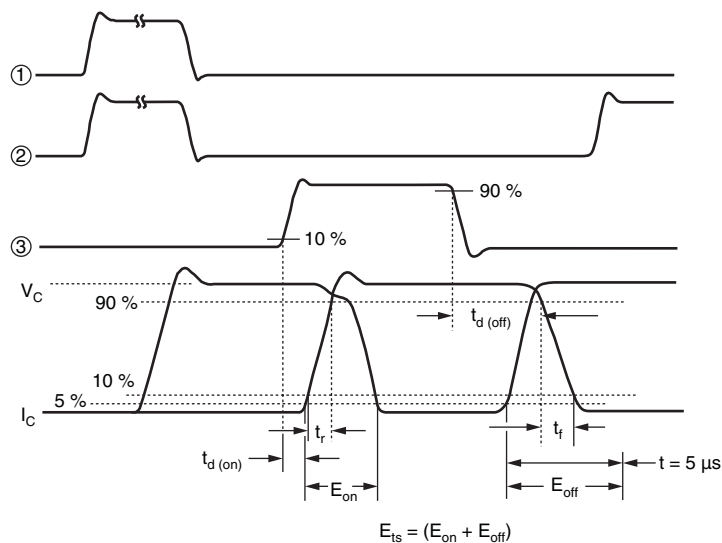
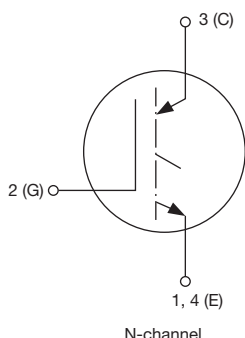
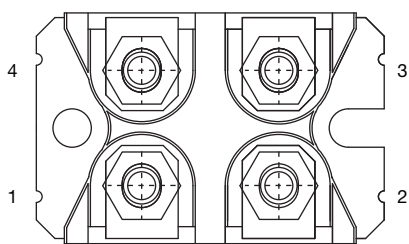


Fig. 17b - Switching Loss Waveforms

ORDERING INFORMATION TABLE

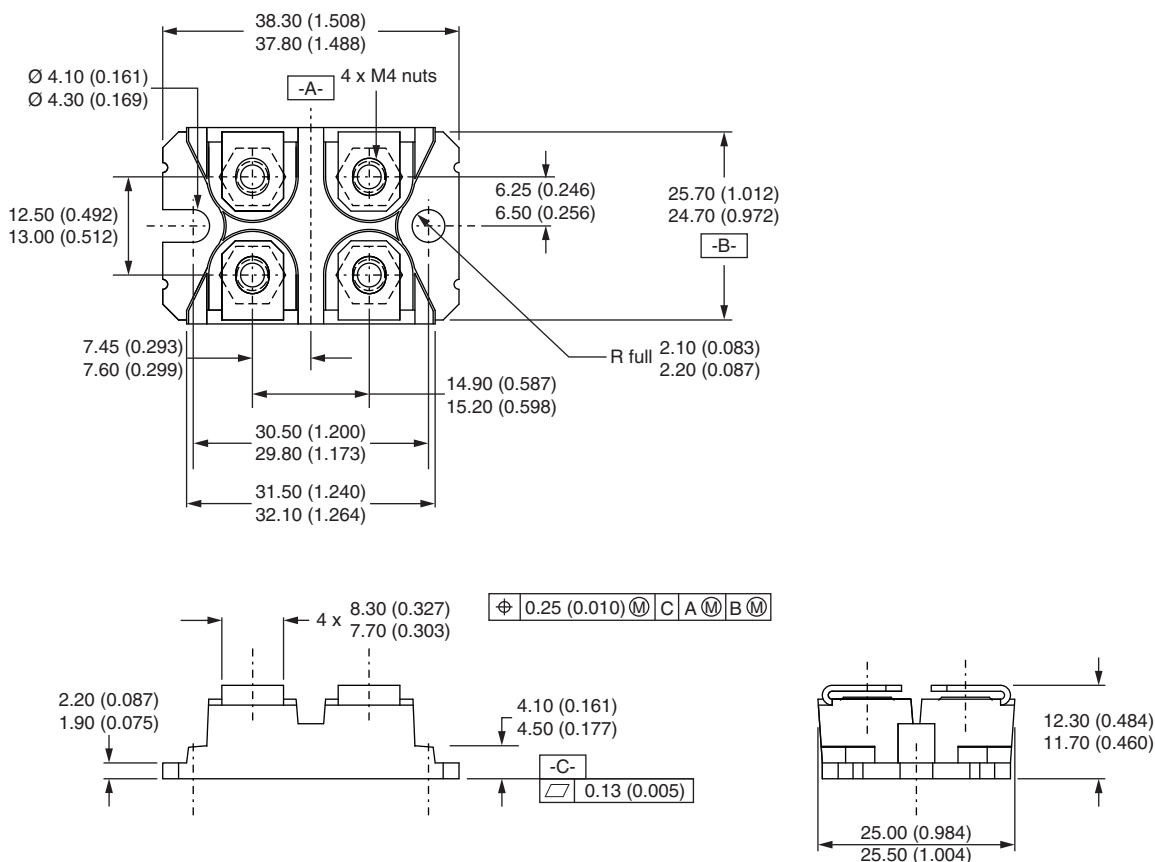
Device code	VS-	G	A	250	S	A	60	S
	1	2	3	4	5	6	7	8
1	- Vishay Semiconductors product							
2	- Insulated Gate Bipolar Transistor (IGBT)							
3	- Generation 4, IGBT silicon							
4	- Current rating (250 = 250 A)							
5	- Circuit configuration (S = Single switch, without antiparallel diode)							
6	- Package indicator (A = SOT-227)							
7	- Voltage rating (60 = 600 V)							
8	- Speed/type (S = Standard speed)							

CIRCUIT CONFIGURATION		
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Single switch, no antiparallel diode	S	 <p>Lead Assignment</p> 

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95423
Packaging information	www.vishay.com/doc?95425

SOT-227 Generation II

DIMENSIONS in millimeters (inches)



Note

- Controlling dimension: millimeter



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